



## Material Content Data Sheet



<b>Sales Product Name</b>				IPD60R600E6		<b>Issued</b>		17. October 2014	
<b>MA#</b>				MA001182900					
<b>Package</b>				PG-TO252-3-313		<b>Weight*</b>		318.73 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	3.063	0.96	0.96	9610	9610	
leadframe	non noble metal	iron	7439-89-6	0.147	0.05		462		
	inorganic material	phosphorus	7723-14-0	0.044	0.01		139		
	non noble metal	copper	7440-50-8	147.096	46.15	46.21	461514	462115	
wire	non noble metal	aluminium	7429-90-5	0.545	0.17	0.17	1710	1710	
encapsulation	organic material	carbon black	1333-86-4	1.406	0.44		4412		
	plastics	epoxy resin	-	24.611	7.72		77217		
	inorganic material	silicondioxide	60676-86-0	114.616	35.96	44.12	359609	441238	
leadfinish	non noble metal	tin	7440-31-5	3.740	1.17	1.17	11734	11734	
plating	inorganic material	phosphorus	7723-14-0	0.003	0.00		11		
	non noble metal	nickel	7440-02-0	1.421	0.45	0.45	4457	4468	
solder	noble metal	silver	7440-22-4	0.071	0.02		222		
	non noble metal	tin	7440-31-5	0.057	0.02		178		
	non noble metal	lead	7439-92-1	2.702	0.85	0.89	8478	8878	
heatspreader	non noble metal	iron	7439-89-6	0.019	0.01		60		
	inorganic material	phosphorus	7723-14-0	0.006	0.00		18		
	non noble metal	copper	7440-50-8	19.177	6.02	6.03	60169	60247	
*deviation	< 10%			Sum in total:		100.00		1000000	

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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